

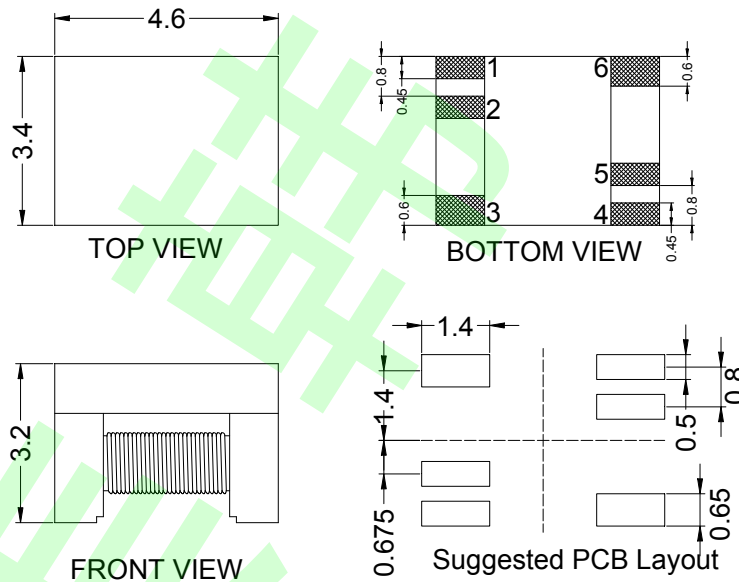
Features:

- Designed For 5G BASE-T Applications, Surface Mount Type.
- Meets IEEE 802.3an Standards
- RoHS compliant

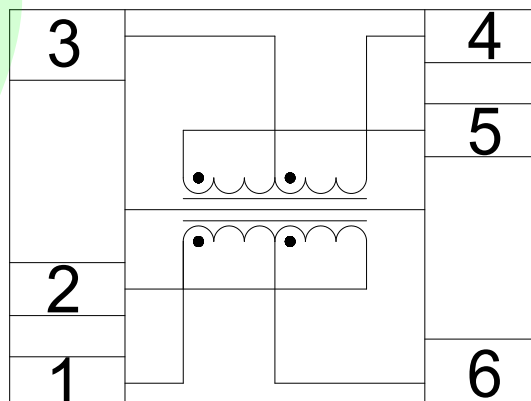
Specifications:

Specifications: at 25 degree Operating Temperature -40°C to +85°C						
Part NO	OCL(100KH z/0.1V 10.8mA DC)	Turns Ratio	DCR	CWW	HI-POT	
UKCLX4634 -151SR	uH	/	Ω	pF	VAC	
	150Min	1:1±5%	1.2Max	35Max	1500	
Part NO	Insertion Loss(dB Max)			Return Loss (dB Min)		
UKCLX4634 -151SR	1-50MHz	50-125MHz	125- 250MHz	1-40MHz	40-250MHz	
	-0.5	-1.0	-2.0	-23	-23+10*Log(F/40)	

Dimension:mm

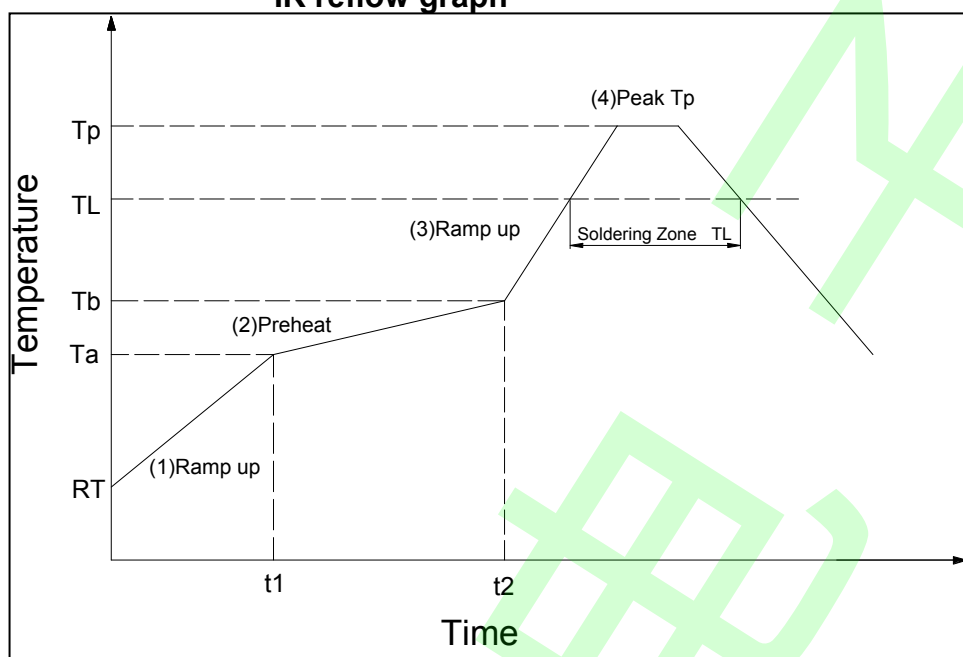


Schematic



5.SUGGEST PROFILE

IR reflow graph



IR reflow profile

Form-1 (Reference JEDEC J-STD-020C Table 5-2))

IR reflow profile		Sn-Pb	Pb-free
step#	Profile Feature	Condition/Duration	Condition/Duration
step1	Ramp-up rate	1.5-3°C/sec.	1.5-3°C/sec.
step2	Preheat : 100~150°C(Ta-Tb)	t1-t2 : 60~120 sec.	t1-t2 : 60~180 sec.
step3	Ramp-up rate(T _L to T _p)	1.5-3°C/sec.	1.5-3°C/sec.
	Temperature maintained above 183°C(T _L)	T _L : 60-150sec.	T _L : 80-150sec.
step4	Peak temperature(T _p)	230+5/-10°C	260+0/-5°C
	Time within 5°C of actual peak temperature	30±10 sec.	30±10 sec.
step5	Ramp-down rate	6°C/sec.Max	6°C/sec.Max
Note1	Subject the samples to 3 cycles of the above defined reflow conditions		Subject the samples to 3 cycles of the above defined reflow conditions
Note2	Time 25°C to peak temperature : 6 minutes max.		Time 25°C to peak temperature : 8 minutes max.
Note3	The time between reflows shall be 5 minutes minimum and 60minutes maximum		

SnPb Eutectic Process- "Package Peak Reflow Temperature"

Form-2 (Reference JEDEC J-STD-020C Table 4-1)

产品厚度	产品体积 < 350mm ³	产品体积 ≥ 350mm ³
< 2.5mm	240 +0/-5°C	225 +0/-5°C
≥ 2.5mm	225 +0/-5°C	225 +0/-5°C

Pb-free Process - "Package Peak Reflow Temperature"

Form-3 (Reference JEDEC J-STD-020C Table 4-2)

产品厚度	产品体积 < 350mm ³	产品体积 350mm ³ - 2000mm ³	产品体积 > 2000mm ³
< 1.6mm	260 +0/-5°C	260 +0/-5°C	260 +0/-5°C
1.6mm-2.5mm	260 +0/-5°C	250 +0/-5°C	245 +0/-5°C
> 2.5mm	250 +0/-5°C	245 +0/-5°C	245 +0/-5°C



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REV: A0

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6. Reliability

No.	Test Item	Refer To Standard	Test Condition																					
1	Resistance To Soldering Heat--Convection Reflow	IPC/JEDEC J-STD-020D	1).Peak Temperature: Refer to Specification According to Package Body Thickness And Volume 2).Preheat Temperature and Soak Time: 150~200℃,60~120 Seconds 3).Average Ramp-up Rate: 3℃/Second Max 4).Above 217℃: 60~150 Seconds 5).Peak Temperature-5℃: Over 30 S																					
2	Thermal Shock	IEC68-2-14 Method A	1.Low Temperature:-40℃ 2.High Temperature:125 3.Dwell Time:30 Minutes 4.Transition Time: Less Than 5Minutes 5.Number of Cycles: 10																					
3	High Temperature	IEC68-2-2 Method A	125℃,96Hours																					
4	Low Temperature	IEC68-2-1 Method A	-40℃,96Hours																					
5	Temperature Humidity Cycle	IEC68-2-38	<table border="1"> <thead> <tr> <th>Temp</th> <th>Humidity</th> <th>soak time</th> </tr> </thead> <tbody> <tr> <td>25~65℃</td> <td>93+/-3%RH</td> <td>1.5 hr</td> </tr> <tr> <td>65℃</td> <td>93+/-3%RH</td> <td>4 hr</td> </tr> <tr> <td>65~25℃</td> <td>80~96%RH</td> <td>2.5 hr</td> </tr> <tr> <td>25~65℃</td> <td>93+/-3%RH</td> <td>1.5hr</td> </tr> <tr> <td>65℃</td> <td>93+/-3%RH</td> <td>4hr</td> </tr> <tr> <td>65~25℃</td> <td>80~96%RH</td> <td>2</td> </tr> </tbody> </table>	Temp	Humidity	soak time	25~65℃	93+/-3%RH	1.5 hr	65℃	93+/-3%RH	4 hr	65~25℃	80~96%RH	2.5 hr	25~65℃	93+/-3%RH	1.5hr	65℃	93+/-3%RH	4hr	65~25℃	80~96%RH	2
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6	Vibration	IEC68-2-6	1.Sine Wave 2.Amplitude:0.75mm 3.Frequence:5~500~5Hz 4.Direction: X,Y,Z 5.Number of Sweep Cycles Per Direction:10 6.Duration: 2 Hours Each Direction																					
7	Mechanical Shock	MIL-STD-202	1).Half -Sine Wave 2).Peak Acceleration:50G 3).Duration:11mS 4).Direction: X,Y,Z,-X,-Y,-Z 5).Number of Shock Per Direction:3																					
8	Free Drop	ISO4180	1) Height: Refer to Specification According to Production weight 2).1Corner,3Edges,6Faces .Total Are 10 Times																					
9	Solderability	JESD22-B102D	1).Precondition:150±5℃,16±0.5Hours 2).Flux Type:ROL1 3).Immersion Flux Time: 5~10 Seconds 4).Solder Temperature:245±5℃ 5).Solder Immersion Time:5±0.5 Seconds 6).Solder Immersion/Emersion Speed:25.4±6.4mm/Second																					
10	Accelerated Moisture Resistance---Unbiased Autoclave	JESD22-A102-C	1.Temperature:121℃ 2. Humidity: 100% 3. Vapor Pressure: 29.7 Psia or 205KPa 4.Duration:96 hours																					

